

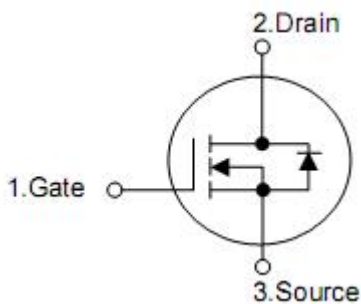
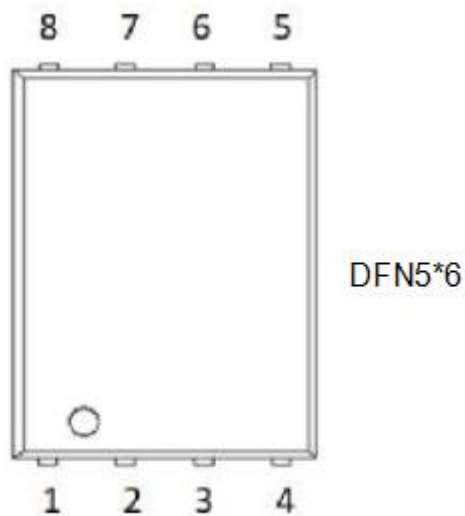
1. Features

- n $R_{DS(on)}=1.8m\Omega$ @ $V_{GS}=10V$
- n Advanced Trench Technology
- n Low Gate Charge
- n High Current Capability
- n RoHS and Halogen-Free Compliant

2. Description

- n Power Management in Desktop Computer
- n DC/DC Converters

3. Symbol



Pin	Function
4	Gate
5,6,7,8	Drain
1,2,3	Source

4. Ordering Information

Part Number	Package	Brand
KCY3303S	DFN5*6	KIA

5. Absolute maximum ratings

Parameter	Symbol	Rating	Units
Drain-source voltage	V_{DS}	30	V
Gate-source voltage	V_{GS}	± 20	V
Continuous drain current $V_{GS}@10V^{1,6}$	I_D	$T_C=25^\circ C$	95
		$T_C=100^\circ C$	76
Pulsed drain current ²	I_{DM}	280	A
Single pulse avalanche energy ³	EAS	151	mJ
Avalanche current	I_{AS}	55	A
Total power dissipation ⁴	P_D	48	W
Junction and storage temperature range	T_J, T_{STG}	-55 to 150	$^\circ C$

6. Thermal Data

Parameter	Symbol	Ratings	Units
Thermal resistance, junction-ambient ¹	$R_{\theta JA}$	50	$^\circ C/W$
Thermal resistance, Junction-case ¹	$R_{\theta Jc}$	2.6	

7. Electrical characteristics

($T_J=25^{\circ}\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Drain-Source breakdown voltage	BV_{DSS}	$V_{GS}=0V, I_D=-250\mu A$	30	-	-	V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=24V, V_{GS}=0V, T_J=25^{\circ}\text{C}$	-	-	1	μA
		$V_{DS}=24V, V_{GS}=0V, T_J=55^{\circ}\text{C}$	-	-	5	
Gate-source leakage current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	± 100	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.2	1.6	2.5	V
Static drain-source on- resistance ²	$R_{DS(on)}$	$V_{GS}=10V, I_D=20A$	-	1.8	2.4	m Ω
		$V_{GS}=4.5V, I_D=20A$	-	2.5	3.8	
Forward transconductance	g_{FS}	$V_{DS}=5V, I_D=20A$	-	90	-	S
Gate Resistance	R_g	$V_{GS}=0V, V_{DS}=0V, F=1\text{MHz}$	-	1.6	-	Ω
Total gate charge(4.5V)	Q_g	$V_{DS}=15V, V_{GS}=10V$ $I_D=20A$	-	20	-	nC
Gate-source charge	Q_{gs}		-	12	-	
Gate-drain charge	Q_{gd}		-	14.5	-	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=15V,$ $R_G=3.3\Omega, V_{GS}=10V$ $I_D=-20A$	-	11	-	ns
Rise time	t_r		-	6	-	
Turn-off delay time	$t_{d(off)}$		-	38	-	
Fall time	t_f		-	11	-	
Input capacitance	C_{iss}	$V_{GS}=0V, V_{DS}=15V$ $F=1.0\text{MHz}$	-	3030	-	pF
Output capacitance	C_{oss}		-	1580	-	
Reverse transfer capacitance	C_{rss}		-	205	-	
Diode characteristics						
Continuous source current ^{1,6}	I_S	$V_G=V_D=0V, \text{Force current}$	-	-	95	A
Diode forward voltage ²	V_{SD}	$V_{GS}=0V, I_S=1A, T_J=25^{\circ}\text{C}$	-	-	1.4	V

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{DD}=25V, V_{GS}=10V, L=0.1\text{mH}, I_{AS}=55A$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.
- 6.Package limitation current is 85A.

8. Test circuits and waveforms

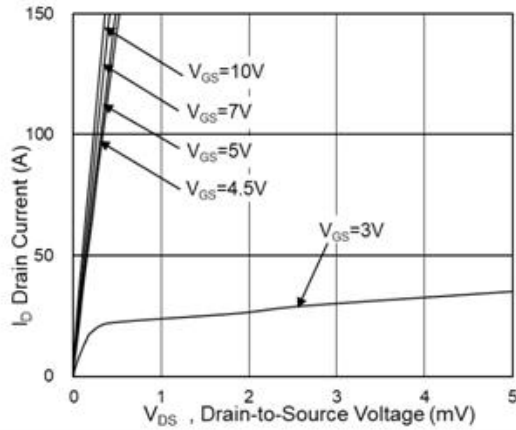


Fig.1 Typical Output Characteristics

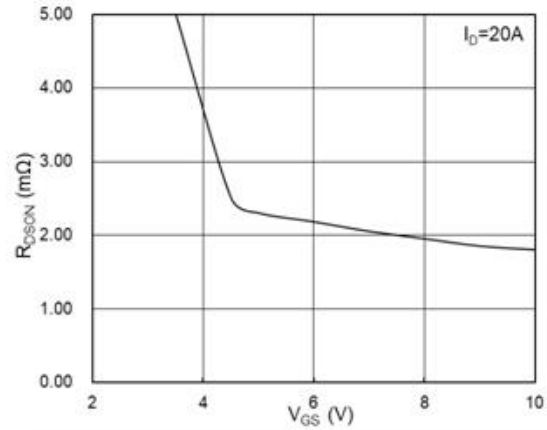


Fig.2 On-Resistance vs G-S Voltage

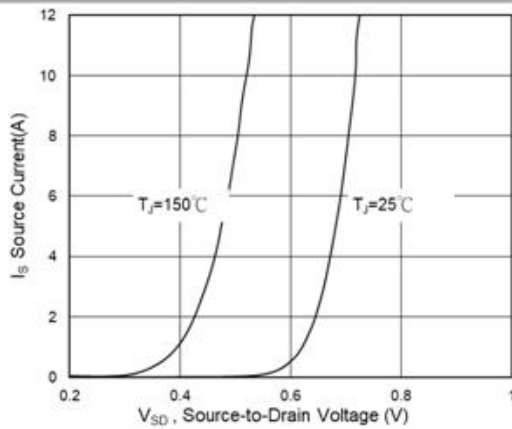


Fig.3 Source Drain Forward Characteristics

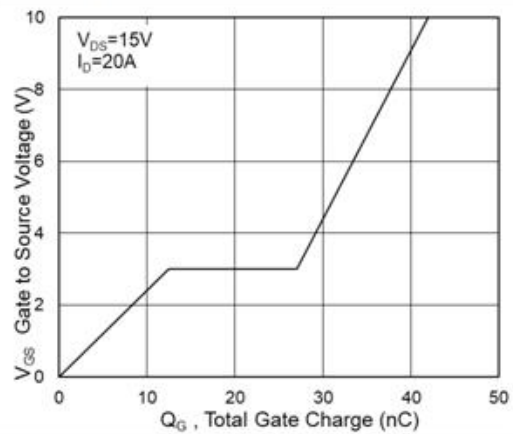


Fig.4 Gate-Charge Characteristics

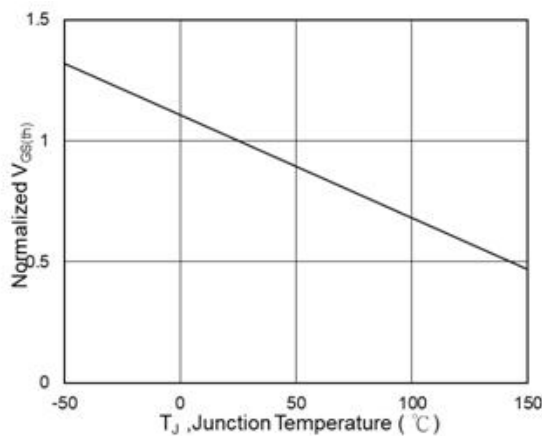


Fig.5 Normalized $V_{GS(th)}$ vs T_J

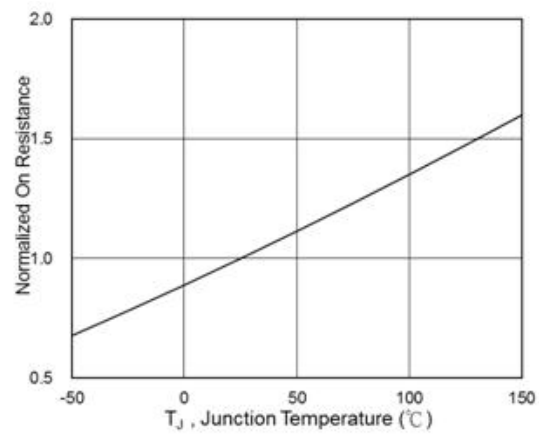


Fig.6 Normalized $R_{DS(on)}$ vs T_J

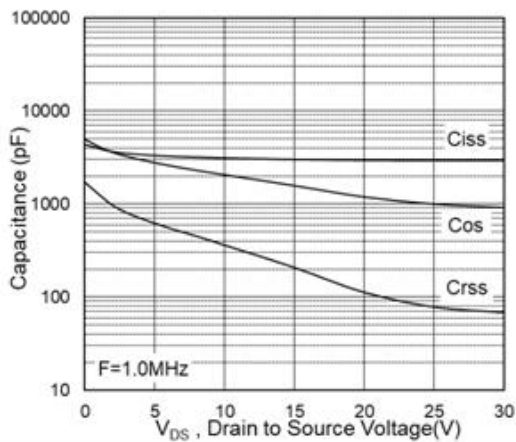


Fig.7 Capacitance

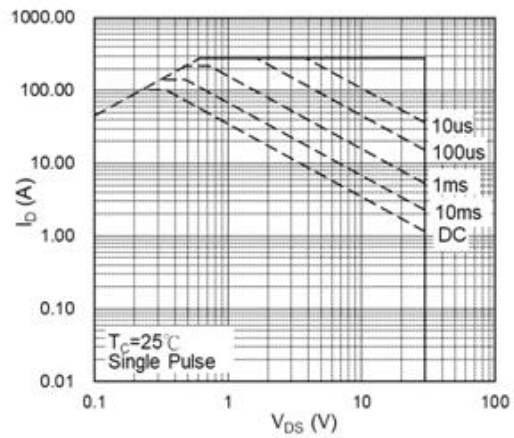


Fig.8 Safe Operating Area

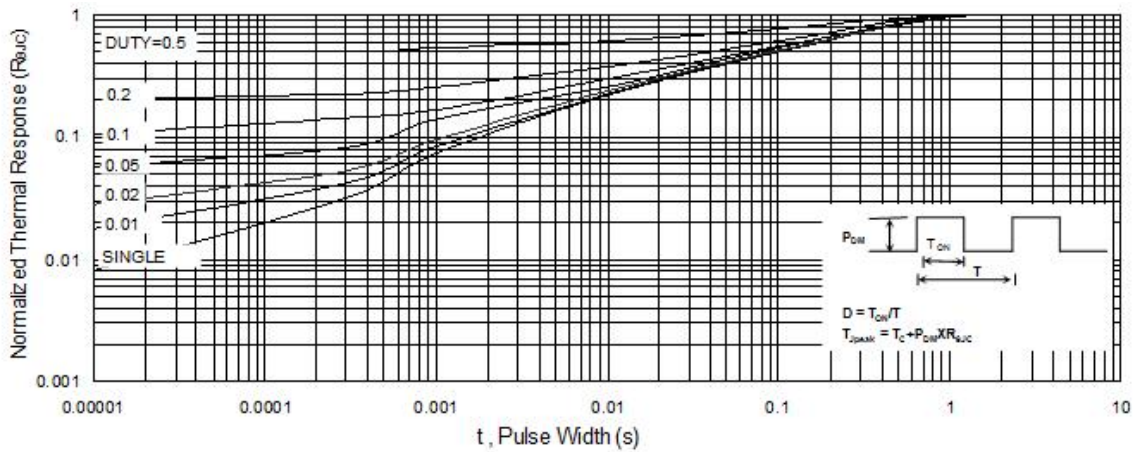


Fig.9 Normalized Maximum Transient Thermal Impedance

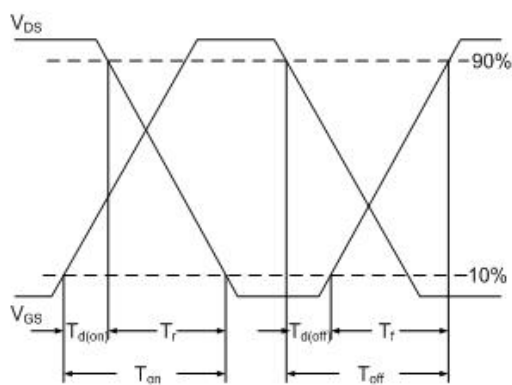


Fig.10 Switching Time Waveform

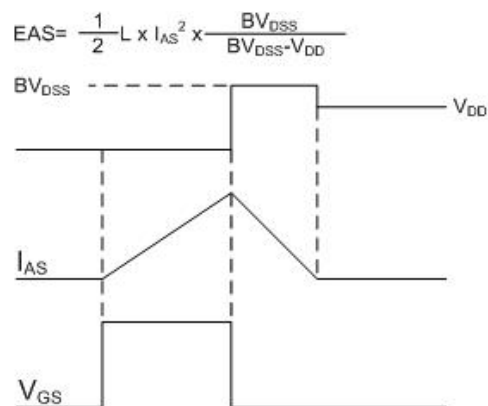


Fig.11 Unclamped Inductive Switching Waveform